

## SPECIFICATION OF LED CHIP

C700-40

[INFRARED]

### 1) Commodity Type and Physical Characteristics.

- |                      |             |                   |                 |
|----------------------|-------------|-------------------|-----------------|
| 1. Material          | GaAlAs      |                   |                 |
| 2. Electrode         | Top Side    | N ( cathode )side | :Au Alloy & Pad |
|                      | Bottom Side | P ( anode )side   | :Au Alloy       |
| 3. Electrode Pattern | Fig.1       |                   |                 |
| 4. Chip Size         | Fig.2       |                   |                 |
| 5. Chip Thickness    | Fig.2       |                   |                 |
| 6. Emission Area     | Fig.2       |                   |                 |

### 2) Electro-Optical Characteristics [Ta=25°C]

Parameters	Symbol	Condition	min.	typ.	max.	Unit
Forward Voltage	Vf	If=20mA		1.8	2.2	V
Reverse Current	Ir	Vr=5V			10	uA
Power Intensity	Po	If=20mA	1.0	2.0		mW
Peak Wavelength	$\lambda_P$	If=20mA		700		nm
Spectral Radiation Bandwidth	$\Delta\lambda$	If=20mA		20		nm
Rise Time	tr	If=20mA		80		ns
Full time	tf	If=20mA		80		ns

‡ Die shall be mounted on TO=18 gold header without resin coated.

[Unit : um]

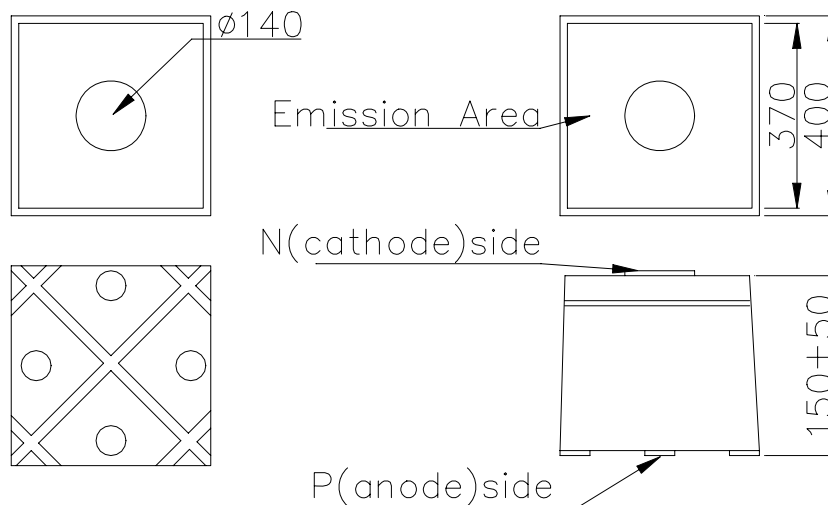


Fig.1 Electrode Pattern

Fig.2 Chip size and Emission Area

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